

adequately addresses the Examiner's concerns regarding the disclosed reaction schemes. By the accompanying amendment, claim 1 has been amended to clearly recite which reactants are reacted and when. It is believed that the amendment overcomes the rejection.

Reconsideration and allowance are respectfully requested in view of the foregoing.

Respectfully submitted,



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Version with Markings to Show Changes Made

1. (Twice amended) A urethane oligomer (A) or the salt thereof obtained by reacting a polyol compound (a) with a polybasic acid anhydride (b-1) having two acid anhydride groups per molecule, subsequently reacting the product thereof with a polyisocyanate compound (c) to form a urethane prepolymer, and reacting said urethane prepolymer with [and] a hydroxy compound having ethylenically unsaturated groups[, successively].

2. (Twice amended) A urethane oligomer (A) or salt thereof according to Claim 1, wherein said polybasic acid anhydride (b-1) having [at least] two acid anhydride groups per molecule has an acid value of 200-1500mgKOH/g [and the salt thereof].

3. (Amended) A urethane oligomer (A) or salt thereof according to claim 1 or 2, wherein said urethane oligomer (A) has a weight-average molecular weight of 1,000-100,000[; and the salt thereof].

4. (Amended) A urethane oligomer (A) or a salt thereof according to claim 1, wherein said urethane oligomer (A) has an acid value of 1-200mgKOH/g [and the salt thereof].

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Replacement Sheet

1. (Twice amended) A urethane oligomer (A) or the salt thereof obtained by reacting a polyol compound (a) with a polybasic acid anhydride (b-1) having two acid anhydride groups per molecule, subsequently reacting the product thereof with a polyisocyanate compound (c) to form a urethane prepolymer, and reacting said urethane prepolymer with a hydroxy compound having ethylenically unsaturated groups.

B 1  
2. (Twice amended) A urethane oligomer (A) or salt thereof according to Claim 1, wherein said polybasic acid anhydride (b-1) having two acid anhydride groups per molecule has an acid value of 200-1500mgKOH/g.

3. (Twice amended) A urethane oligomer (A) or salt thereof according to claim 1 or 2, wherein said urethane oligomer (A) has a weight-average molecular weight of 1,000-100,000.

4. (Twice amended) A urethane oligomer (A) or a salt thereof according to claim 1, wherein said urethane oligomer (A) has an acid value of 1-200mgKOH/g.

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Replacement Sheet

1. (Twice amended) A urethane oligomer (A) or the salt thereof obtained by reacting a polyol compound (a) with a polybasic acid anhydride (b-1) having two acid anhydride groups per molecule, subsequently reacting the product thereof with a polyisocyanate compound (c) to form a urethane prepolymer, and reacting said urethane prepolymer with a hydroxy compound having ethylenically unsaturated groups.

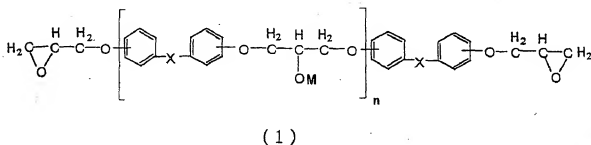
B 2. (Twice amended) A urethane oligomer (A) or salt thereof according to Claim 1, wherein said polybasic acid anhydride (b-1) having two acid anhydride groups per molecule has an acid value of 200-1500mgKOH/g.

3. (Twice amended) A urethane oligomer (A) or salt thereof according to claim 1 or 2, wherein said urethane oligomer (A) has a weight-average molecular weight of 1,000-100,000.

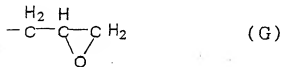
4. (Twice amended) A urethane oligomer (A) or a salt thereof according to claim 1, wherein said urethane oligomer (A) has an acid value of 1-200mgKOH/g.

5. (Amended) A resin composition comprising a urethane oligomer (A) according to claim 1 and an unsaturated group-containing polycarboxylic acid resin (B) that is a product obtained by reacting an epoxy resin (e) having at least two epoxy groups per molecule with a monocarboxylic acid compound (f) having ethylenically unsaturated groups and a polybasic acid anhydride (b-2).

(6) A resin composition according to Claim (5), wherein said epoxy resin (e) having at least two epoxy groups per molecule is represented by Formula (1):



(In the formula, X is  $-\text{CH}_2-$  or  $-\text{C}(\text{CH}_3)_2-$ , n is an integer of 1 or more, and M is hydrogen or a group represented by Formula (G) as shown below:



, provided that M is a group represented by Formula (G) if n is 1, while at least one M is a group represented by Formula (G) and each the remainders being hydrogen if n is an integer more than 1).

7. (Amended) A resin composition comprising a urethane oligomer (A) according to claim 1 and a thermoplastic polymer (D).

8. (Amended) A resin composition according to claim 5, comprising a diluent (C).

9. (Amended) A resin composition according to claim 5, further comprising a diluent (C), and wherein said diluent (C) is a reactive diluent (C-1).

10. (Amended) A resin composition according to claim 5 comprising a photopolymerization initiator (E).

11. (Amended) A resin composition comprising a urethane oligomer (A) according to claim 1, a thermoplastic polymer (D) and a photopolymerization initiator (E).

(12) A resin composition according to Claim (11), wherein said thermoplastic polymer (D) is a polymer having carboxyl groups.

13. (Amended) A resin composition according to claim 5 comprising a thermoplastic component (F).

14. (Amended) A resin composition according to claim 5, wherein said resin composition is prepared for the solder resist in a printed circuit board or for an interlayer dielectric layer.

15. (Amended) A photosensitive film comprising being prepared by laminating the layer of a resin composition according to claim 5 on a supporting film.

(16) A photosensitive film according to Claim (15), wherein said photosensitive film is prepared for a printed circuit board.

17. (Amended) A cured product of the resin composition according to claim 5.

(18) An article comprising having the layer of a cured product according to Claim (17).

(19) An article according to Claim (18), wherein said article is a printed circuit board.